N800C





Non-Silicone Thermal Conductive Pad

Non-Silicone Thermal Compound N800C is made of non-silicon resin material. No low molecular siloxane volatilization and low total volatile gas, no electrical contact & pollution problems. N800C is flexible and has great thermal conduction, Low compressive stress and high compressive characteristics can effectively reduce the stress load of components, so that the equipment only needs to bear less mechanical stress, and at the same time, it can have low thermal resistance and high thermal conductivity.

■ FEATURES

- / Thermal conductivity:17.0 W/m*K / It's made by non-silicone resin materials
- / Low contact thermal resistance
- / With electrical insulation
- / Outstanding thermal conductivity
- / Applicable to optical and sensitive electric components

■ TYPICAL APPLICATION

- / HDDS
- / Optical appliance
- / 5G base station & infrastructure
- / EV electric vehicle

■ SPECIFICATIONS

- / Sheet form
- / Die-cut parts



■ TYPICAL PROPERTIES

- THIOALTROI ERTIES			
PROPERTY	N800C	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.3	ASTM D792	g/cm³
Hardness	50	ASTM D2240	Shore OO
Tensile Strength	0.15	ASTM D412	Kgf/cm ²
Application temperature	-60~125	-	°C
Low molecular Siloxane (D3 to D20 total)	N.D	Gas Chromatography	%
Outgassing CVCM (wt%)	0.0043	By LiPOLY	-
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	8	ASTM D5470 modify	%
Deflection @20 psi	28	ASTM D5470 modify	%
Deflection @30 psi	55	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	8	ASTM D149	KV/mm
Surface resistivity	>1011	ASTM D257	Ohm
Volume resistivity	>1010	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	17.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.122	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.103	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.058	ASTM D5470	°C-in²/ W
(D3 to D20 total) Outgassing CVCM (wt%) ROHS & REACH COMPRESSION@1.0mm Deflection @10 psi Deflection @20 psi Deflection @30 psi ELECTRICAL Dielectric breakdown Surface resistivity Volume resistivity THERMAL Thermal Conductivity Thermal impedance@10 psi Thermal impedance@20 psi	0.0043 Compliant 8 28 55 8 >10¹¹ >10¹⁰ 17.0 0.122 0.103	Chromatography By LiPOLY - ASTM D5470 modify ASTM D5470 modify ASTM D5470 modify ASTM D149 ASTM D257 ASTM D257 ASTM D257 ASTM D5470 ASTM D5470 ASTM D5470 ASTM D5470	- % % % % KV/mn Ohm Ohm-n W/m*k °C-in²/\

The chemical formula indicates that if Cyclic polydimethylsilox-ane (HO-[Si(CH3)20]n-H) is non-reaction, it's volatile anytime and everywhere. For example, when the electric products which has been put in a confined space, the volatile of low-molecular-weight silox-anes will makes the elecetic products uncontacted.

Thermal Resistance vs. Pressure vs. Deflection

